

Tyrone Camarero Specifications



Camarero SDI100A2R-216H

Key features

High Performance Computing, Enterprise Server, Data Center Optimized, Database Processing and High Density Storage Application-Optimized Solutions

- Dual Socket P+ (LGA-4189), 3rd Gen Intel® Xeon® Scalable processors, Support CPU TDP 270W, UPI up to 11.2 GT/s
- Intel® C621A Chipset
- Up to 4TB 3DS ECC RDIMM, DDR4-3200MHz, Up to 4TB 3DS ECC LRDIMM, DDR4-3200MHz Up to 4TB Intel® Optane™ Persistent Memory 200 Series, DDR4-3200MHz, in 18 DIMM slots (P1-DIMMB2 and P2-DIMMB2 are reserved for Intel® Optane Persistent Memory 200 Series only)
- 4 PCI-E 4.0 x16 Low Profile (LP), 1 PCI-E 4.0 x8 Low Profile (LP)
- PCI-E slot#1 is populated with 1x AOC-S3908L-H8IR-16DD-P to support 8x SAS drives
- Dual Gigabit LAN with Intel® i350 Ethernet Controller
Optional : Dual 10GBase-T LAN with Intel® X550 Ethernet Controller
- 16 hotswap 2.5" drive bays, 8 SAS drives with Broadcom® 3908 Gen4 HW RAID controller for RAID 0, 1, 5, 6, 10, 50, 60
8 SATA drives with Intel® C621A controller for RAID 0,1,5,10,1 M.2 support:M.2 Interface: PCI-E 3.0 x4, M.2 Form Factor: 2260, 2280, 22110, M.2 Key: M-Key, Optional 1 slim or 5.25" DVD-ROM drive, Optional 4x hotswap 2.5" NVMe or 2 fixed 2.5" NVMe/SSD/HDD/SuperDOM"
- 3 heavy duty Hot-swappable 13.5K RPM Middle Cooling Fans with optimal fan speed control 1 air shroud
- 1200W Redundant Power Supplies Titanium level
- 1 rear VGA, 1 Type A port, 2 COM Ports (1 front; 1 rear) and 6 USB ports (2 front USB 2.0 and 4 rear USB 3.0)



Processor/Cache		Front Panel	
Processor	Dual Socket P+ (LGA-4189), 3rd Gen Intel® Xeon® Scalable processors, Support CPU TDP 270W, UPI up to 11.2 GT/s	LEDs	HDD activity, Network activity, Power status, System information (overheat/UID)
		Buttons	Power On/Off, System Reset
Chipset		Drive Bays	
Chipset	Intel® C621A	HDD Bays	16x 2.5" hot-swap drive bays (8x SAS drive bays with Broadcom® 3908 HW RAID controller (backplane port# 0~7) and 8x SATA drive bays (backplane port# 8~15) with Intel® C621A (4x SATA drive bays (backplane port# 8~11) can be converted to NVMe drives with optional 2x CBL-SAST-0821-1), 1 M.2 NVMe
		Peripheral Bays	1x (slim or 5.25") DVD drive bays (optional)
System Memory		Power Supply	
Memory Capacity	Up to 4TB 3DS ECC RDIMM, DDR4-3200MHz, Up to 4TB 3DS ECC LRDIMM, DDR4-3200MHz Up to 4TB Intel® Optane™ Persistent Memory 200 Series, DDR4-3200MHz, in 18 DIMM slots (P1-DIMMB2 and P2-DIMMB2 are reserved for Intel® Optane Persistent Memory 200 Series only)	1200W Redundant Power Supplies Titanium level	
Expansion Slots		Cooling System	
PCI-Express	4 PCI-E 4.0 x16 Low Profile (LP), 1 PCI-E 4.0 x8 Low Profile (LP) PCI-E slot#1 is populated with 1x AOC-S3908L-H8IR-16DD-P to support 8x SAS drives	3 heavy duty fans with optimal fan speed control	
Integrated Onboard		Form Factor	
Network Connectivity	2x 1GbE port(s) Optional : 2x 10GbE port(s)	Form Factor	2U Rackmount
LAN	1 Dedicated IPMI LAN port	Dimensions:	Height : 3.5" (89mm), Width : 17.2" (437mm), Depth : 24.8" (630mm)
Add-on Options		<p>Email : info@tyronesystems.com</p> <p>For more/current product information, visit</p> <p>www.tyronesystems.com</p>	
Optical Drive	Optional		

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